

Octal D Flip-Flop with Common Clock and Reset

High-Performance Silicon-Gate CMOS

MC74HC273A, MC74HCT273A

The MC74HC273A/MC74HCT273A is identical in pinout to the LS273. The MC74HC273A inputs are compatible with Standard CMOS outputs; with pull-up resistors, the device is compatible with LSTTL outputs. The MC74HCT273A may be used as a level converter for interfacing TTL or NMOS outputs to high speed CMOS inputs.

The HC273A/HCT273A consists of eight D flip-flops with common Clock and Reset inputs. Each flip-flop is loaded with a low-to-high transition of the Clock input. Reset is asynchronous and active low.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2.0 to 6.0 V (HC), 4.5 to 5.5 V (HCT)
- Low Input Current: 1.0 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7 A
- Chip Complexity: 284 FETs or 71 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

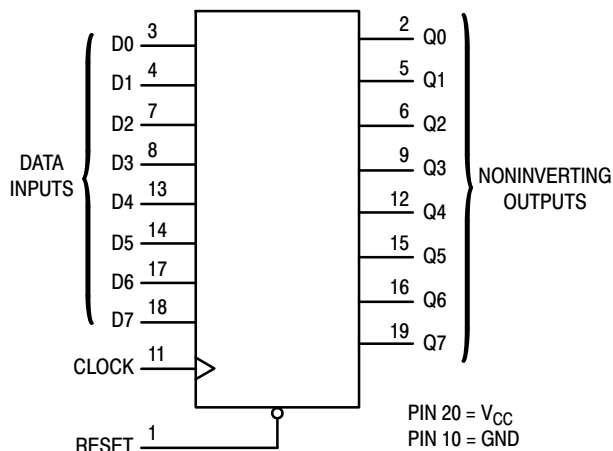
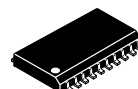


Figure 1. Logic Diagram



SOIC-20
DW SUFFIX
CASE 751D

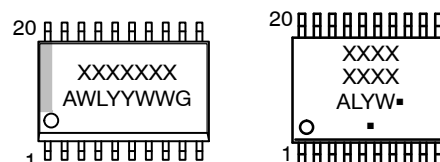


TSSOP-20
DT SUFFIX
CASE 948E

PIN ASSIGNMENT

RESET	1	20	V _{CC}
Q0	2	19	Q7
D0	3	18	D7
D1	4	17	D6
Q1	5	16	Q6
Q2	6	15	Q5
D2	7	14	D5
D3	8	13	D4
Q3	9	12	Q4
GND	10	11	CLOCK

MARKING DIAGRAMS



SOIC-20

XXXXXXXX = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

TSSOP-20

(Note: Microdot may be in either location)

FUNCTION TABLE

Inputs			Output
Reset	Clock	D	Q
L	X	X	L
H	↗	H	H
H	↘	L	L
H	L	X	No Change
H	↖	X	No Change

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

MC74HC273A, MC74HCT273A

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		−0.5 to +6.5	V
V _{IN}	DC Input Voltage		−0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage		−0.5 to V _{CC} +0.5	V
I _{IN}	DC Input Diode Current, per Pin		±20	mA
I _{OUT}	DC Input Diode Current, Per Pin		±35	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins		±75	mA
I _{IK}	Input Clamp Current (V _{IN} < 0 or V _{IN} > V _{CC})		±20	mA
I _{OK}	Output Clamp Current (V _{OUT} < 0 or V _{OUT} > V _{CC})		±20	mA
T _{STG}	Storage Temperature Range		−65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 secs		260	°C
T _J	Junction Temperature Under Bias		+150	°C
θ _{JA}	Thermal Resistance (Note 1)	SOIC−20W WQFN20 QFN20 TSSOP−20	96 99 111 150	°C/W
P _D	Power Dissipation in Still Air at 25°C	SOIC−20W WQFN20 QFN20 TSSOP−20	1302 1256 1127 833	mW
MSL	Moisture Sensitivity	SOIC−20W All Other Packages	Level 3 Level 1	–
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	–
V _{ESD}	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model	> 2000 > 1000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
3. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
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MC74HC

V_{CC}	DC Supply Voltage	2.0	6.0	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Note 4)	0	V_{CC}	V
T_A	Operating Free-Air Temperature	-55	+125	°C
t_r, t_f	Input Rise or Fall Time	$V_{CC} = 2.0$ V $V_{CC} = 4.5$ V $V_{CC} = 6.0$ V	0 1000 500 400	ns

MC74HCT

V_{CC}	DC Supply Voltage	4.5	5.5	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Note 4)	0	V_{CC}	V
T_A	Operating Free-Air Temperature	-55	+125	°C
t_r, t_f	Input Rise or Fall Time	0	500	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

MC74HC273A, MC74HCT273A

DC ELECTRICAL CHARACTERISTICS (MC74HC273A)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				–55 to 25°C	≤ 85°C	≤ 125°C	
V _{IH}	Minimum High–Level Input Voltage	V _{out} = V _{CC} – 0.1 V I _{out} ≤ 20 μA	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V _{IL}	Maximum Low–Level Input Voltage	V _{out} = 0.1 V I _{out} ≤ 20 μA	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V _{OH}	Minimum High–Level Output Voltage	V _{in} = V _{IH} I _{out} ≤ 20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V _{in} = V _{IH} I _{out} ≤ 2.4 mA	3.0	2.48	2.34	2.2	
		I _{out} ≤ 6.0 mA	4.5	3.98	3.84	3.7	
V _{OL}	Maximum Low–Level Output Voltage	V _{in} = V _{IH} I _{out} ≤ 7.8 mA	6.0	5.48	5.34	5.2	V
		V _{in} = V _{IL} I _{out} ≤ 20 μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	
		V _{in} = V _{IL} I _{out} ≤ 2.4 mA	3.0	0.26	0.33	0.4	
I _{in}	Maximum Input Leakage Current	I _{out} ≤ 6.0 mA	4.5	0.26	0.33	0.4	μA
		I _{out} ≤ 7.8 mA	6.0	0.26	0.33	0.4	
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	6.0	4.0	40	160	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS (MC74HC273A)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			–55 to 25°C	≤ 85°C	≤ 125°C	
f _{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 2 and 3)	2.0 3.0 4.5 6.0	6.0 15 30 35	5.0 10 24 28	4.0 8.0 20 24	MHz
t _{PLH} t _{PHL}	Maximum Propagation Delay, Clock to Q (Figures 2 and 3)	2.0 3.0 4.5 6.0	145 90 29 25	180 120 36 31	220 140 44 38	ns
t _{PHL}	Maximum Propagation Delay, Reset to Q (Figures 2 and 3)	2.0 3.0 4.5 6.0	145 90 29 25	180 120 36 31	220 140 44 38	ns
t _{TLH} t _{THL}	Maximum Output Transition Time, Any Output (Figures 2 and 3)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 16	110 36 22 19	ns
C _{in}	Maximum Input Capacitance		10	10	10	pF

C _{PD}	Power Dissipation Capacitance (Per Enabled Output)*	Typical @ 25°C, V _{CC} = 5.0 V	pF
		48	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

*Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}.

MC74HC273A, MC74HCT273A

TIMING REQUIREMENTS (MC74HC273A)

Symbol	Parameter	Figure	V _{CC} Volts	Guaranteed Limit						Unit
				−55 to 25°C		≤ 85°C		≤ 125°C		
				Min	Max	Min	Max	Min	Max	
t _{su}	Minimum Setup Time, Data to Clock	5	2.0 3.0 4.5 6.0	60 23 12 10		75 27 15 13		90 32 18 15		ns
t _h	Minimum Hold Time, Clock to Data	5	2.0 3.0 4.5 6.0	3.0 3.0 3.0 3.0		3.0 3.0 3.0 3.0		3.0 3.0 3.0 3.0		ns
t _{rec}	Minimum Recovery Time, Reset Inactive to Clock	4	2.0 3.0 4.5 6.0	5.0 5.0 5.0 5.0		5.0 5.0 5.0 5.0		5.0 5.0 5.0 5.0		ns
t _w	Minimum Pulse Width, Clock	3	2.0 3.0 4.5 6.0	60 23 12 10		75 27 15 13		90 32 18 15		ns
t _w	Minimum Pulse Width, Reset	4	2.0 3.0 4.5 6.0	60 23 12 10		75 27 15 13		90 32 18 15		ns
t _r , t _f	Maximum Input Rise and Fall Times	3	2.0 3.0 4.5 6.0		1000 800 500 400		1000 800 500 400		1000 800 500 400	ns

MC74HC273A, MC74HCT273A

DC ELECTRICAL CHARACTERISTICS (MC74HCT273A)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				-55 to 25°C	≤ 85°C	≤ 125°C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA	4.5 5.5	2.0 2.0	2.0 2.0	2.0 2.0	V
V _{IL}	Maximum Low-Level Input Voltage	V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA	4.5 5.5	0.8 0.8	0.8 0.8	0.8 0.8	V
V _{OH}	Minimum High-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 4.0 mA	4.5	3.98	3.84	3.7	
V _{OL}	Maximum Low-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 4.0 mA	4.5	0.26	0.33	0.4	
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	5.5	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	5.5	4.0	40	160	μA

ΔI _{CC}	Additional Quiescent Supply Current	V _{in} = 2.4 V, Any One Input V _{in} = V _{CC} or GND, Other Inputs I _{out} = 0 μA	5.5	≥ -55°C	25°C to 125°C	mA
				2.9	2.4	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MC74HC273A, MC74HCT273A

AC ELECTRICAL CHARACTERISTICS (MC74HCT273A)

Symbol	Parameter	Guaranteed Limit			Unit
		-55 to 25°C	≤ 85°C	≤ 125°C	
f _{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 2 and 3)	30	24	20	MHz
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock to Q (Figures 2 and 3)	25	28	35	ns
t _{PHL}	Maximum Propagation Delay, Reset to Q	25	28	35	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 2 and 3)	18	20	22	ns

C _{PD}	Power Dissipation Capacitance (Per Gate)*	Typical @ 25°C, V _{CC} = 5.0 V	pF
		30	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

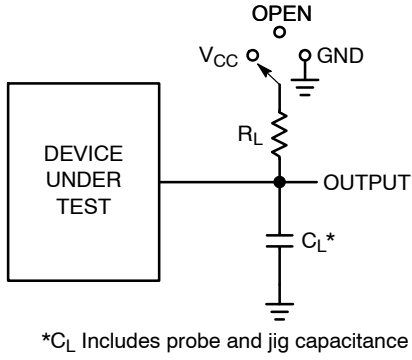
*Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

TIMING REQUIREMENTS (MC74HCT273A)

Symbol	Parameter	Fig.	Guaranteed Limit						Unit
			−55 to 25°C		≤ 85°C		≤ 125°C		
			Min	Max	Min	Max	Min	Max	
t _{su}	Minimum Setup Time, Data to Clock		10		12		15		ns
t _h	Minimum Hold Time, Clock to Data		3.0		3.0		3.0		ns
t _{rec}	Minimum Recovery Time, Set or Reset Inactive to Clock		5.0		5.0		5.0		ns
t _w	Minimum Pulse Width, Clock	4	12		15		18		ns
t _w	Minimum Pulse Width, Set or Reset		12		15		18		ns
t _r , t _f	Maximum Input Rise and Fall Times	3		500		500		500	ns

MC74HC273A, MC74HCT273A

SWITCHING WAVEFORMS



Test	Switch Position	C _L	R _L
t _{PLH} / t _{PHL}	Open	50 pF	1 kΩ
t _{PLZ} / t _{PZL}	V _{CC}		
t _{PHZ} / t _{PZH}	GND		

Figure 2. Test Circuit

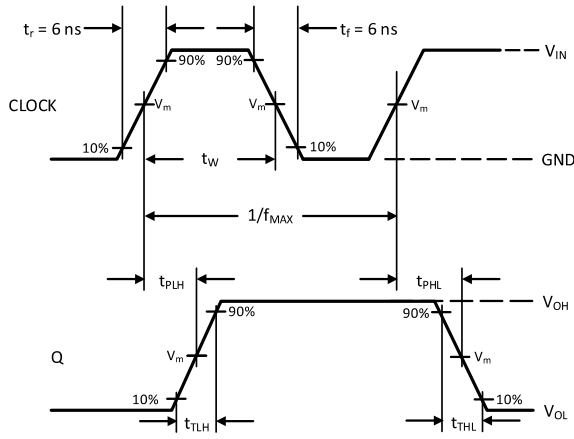


Figure 3.

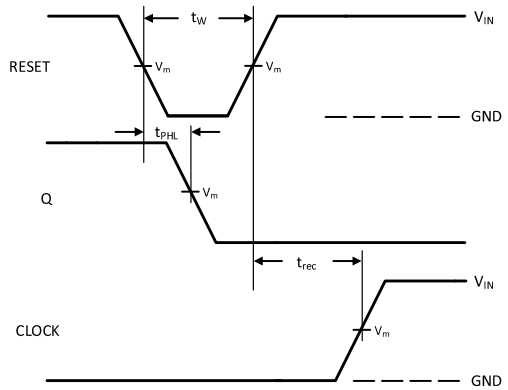


Figure 4.

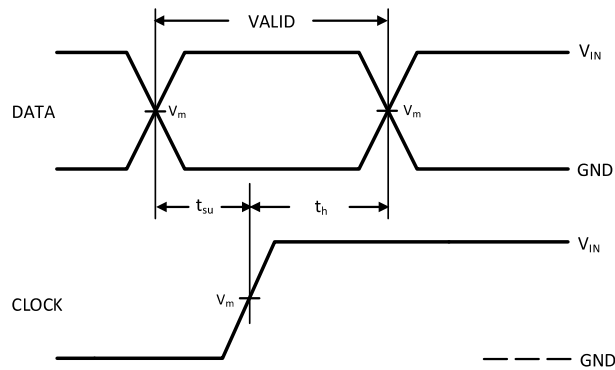


Figure 5.

Device	V _{IN} , V	V _m , V
MC74HC273A	V _{CC}	50% x V _{CC}
MC74HCT273A	3 V	1.3 V

MC74HC273A, MC74HCT273A

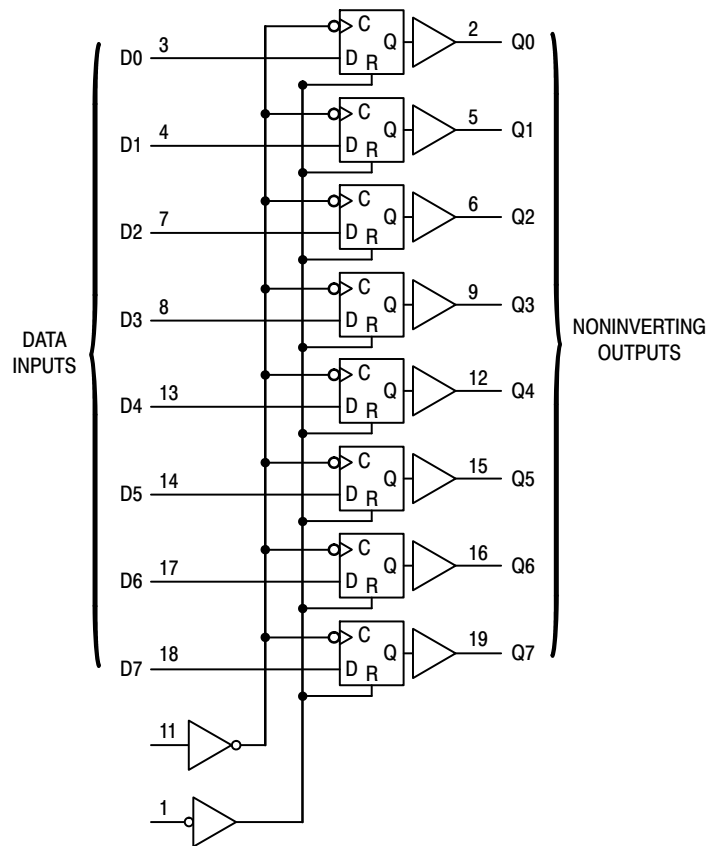


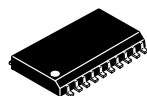
Figure 6. Expanded Logic Diagram

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MC74HC273ADWG	HC273A	SOIC-20 Wide	38 Units / Rail
MC74HC273ADWR2G	HC273A	SOIC-20 Wide	1000 / Tape & Reel
MC74HC273ADWR2G-Q*	HC273A	SOIC-20 Wide	1000 / Tape & Reel
MC74HC273ADTG	HC 273A	TSSOP-20	75 Units / Rail
MC74HC273ADTR2G	HC 273A	TSSOP-20	2500 / Tape & Reel
MC74HC273ADTR2G-Q*	HC 273A	TSSOP-20	2500 / Tape & Reel
MC74HCT273ADWG	HCT273A	SOIC-20 Wide	38 Units / Rail
MC74HCT273ADWR2G	HCT273A	SOIC-20 Wide	1000 / Tape & Reel
MC74HCT273ADWR2G-Q*	HCT273A	SOIC-20 Wide	1000 / Tape & Reel
MC74HCT273ADTR2G	HCT 273A	TSSOP-20	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

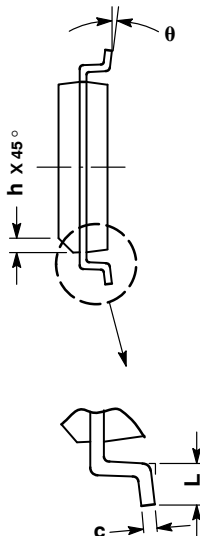
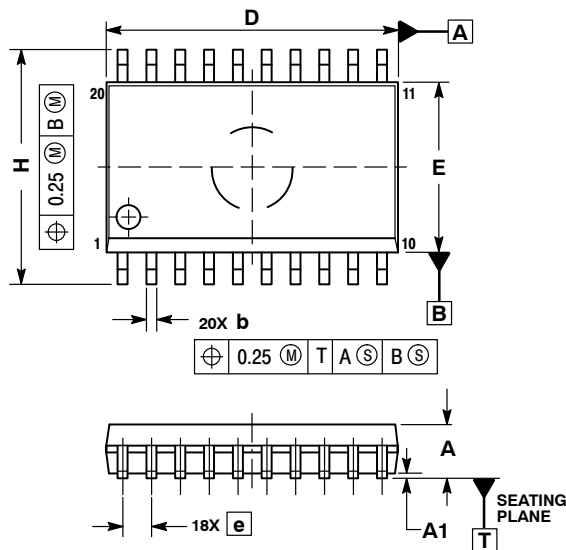
*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



SCALE 1:1

SOIC-20 WB
CASE 751D-05
ISSUE H

DATE 22 APR 2015

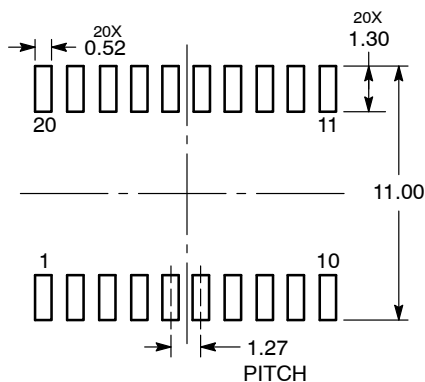


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

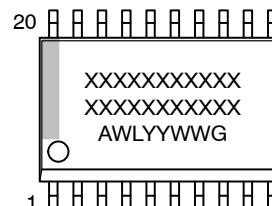
RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*

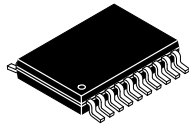


XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

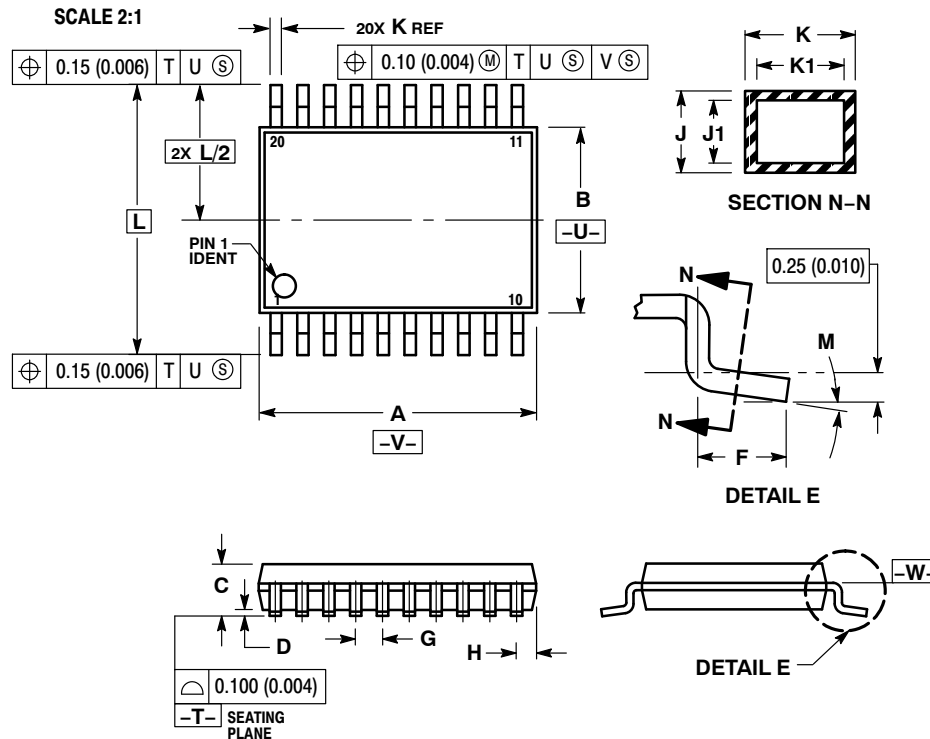
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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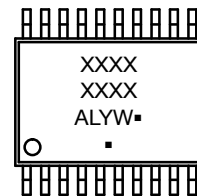

TSSOP-20 WB
CASE 948E
ISSUE D

DATE 17 FEB 2016


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM*


- A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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